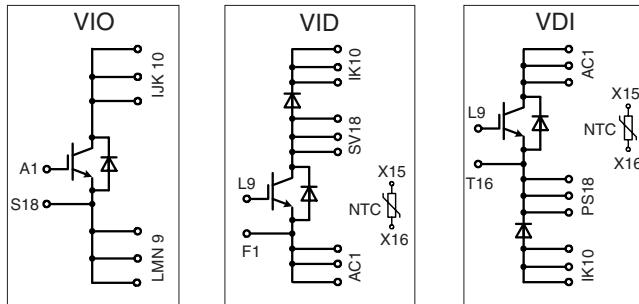


**IGBT Modules** in ECO-PAC 2

Short Circuit SOA Capability  
Square RBSOA

$I_{C25}$  = 169 A  
 $V_{CES}$  = 1200 V  
 $V_{CE(sat)\text{ typ.}}$  = 2.9 V



B3

Pin arrangement see outlines

**IGBTs**

Symbol	Conditions	Maximum Ratings		
$V_{CES}$	$T_{VJ} = 25^\circ\text{C}$ to $150^\circ\text{C}$	1200		V
$V_{GES}$		$\pm 20$		V
$I_{C25}$	$T_c = 25^\circ\text{C}$	169		A
$I_{C80}$	$T_c = 80^\circ\text{C}$	117		A
$I_{CM}$ $V_{CEK}$	$\left. \begin{array}{l} V_{GE} = \pm 15 \text{ V}; R_G = 6.8 \Omega; T_{VJ} = 125^\circ\text{C} \\ \text{RBSOA, Clamped inductive load; } L = 100 \mu\text{H} \end{array} \right\}$	200		A
$t_{sc}$ (SCSOA)	$V_{CE} = V_{CES}; V_{GE} = \pm 15 \text{ V}; R_G = 6.8 \Omega; T_{VJ} = 125^\circ\text{C}$ non-repetitive	10		$\mu\text{s}$
$P_{tot}$	$T_c = 25^\circ\text{C}$	694		W

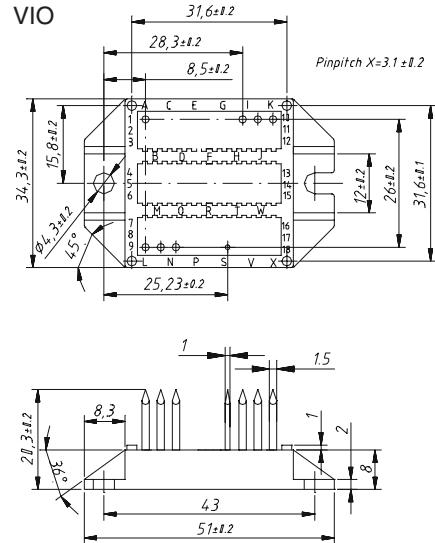
Symbol	Conditions	Characteristic Values		
		( $T_{VJ} = 25^\circ\text{C}$ , unless otherwise specified)		
		min.	typ.	max.
$V_{CE(sat)}$	$I_c = 160 \text{ A}; V_{GE} = 15 \text{ V}; T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$	2.9 3.3	3.5	V
$V_{GE(th)}$	$I_c = 4 \text{ mA}; V_{GE} = V_{CE}$	4.5		V
$I_{CES}$	$V_{CE} = V_{CES}; V_{GE} = 0 \text{ V}; T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$		6 19	mA
$I_{GES}$	$V_{CE} = 0 \text{ V}; V_{GE} = \pm 20 \text{ V}$		400	nA
$t_{d(on)}$ $t_r$ $t_{d(off)}$ $t_f$ $E_{on}$ $E_{off}$	$\left. \begin{array}{l} \text{Inductive load, } T_{VJ} = 125^\circ\text{C} \\ V_{CE} = 600 \text{ V}; I_c = 100 \text{ A} \\ V_{GE} = 15/0 \text{ V}; R_G = 6.8 \Omega \end{array} \right\}$	100 60 600 90 16.1 14.6		ns ns ns ns mJ mJ
$C_{ies}$	$V_{CE} = 25 \text{ V}; V_{GE} = 0 \text{ V}; f = 1 \text{ MHz}$	6.5		nF
$R_{thJC}$ $R_{thJH}$	(per IGBT) with heatsink compound (0.42 K/m.K; 50 $\mu\text{m}$ )	0.36	0.18	K/W

IXYS reserves the right to change limits, test conditions and dimensions.

## Reverse diodes (FRED)

Symbol	Conditions	Maximum Ratings		
I <sub>F25</sub>	T <sub>C</sub> = 25°C	154	A	
I <sub>F80</sub>	T <sub>C</sub> = 80°C	97	A	

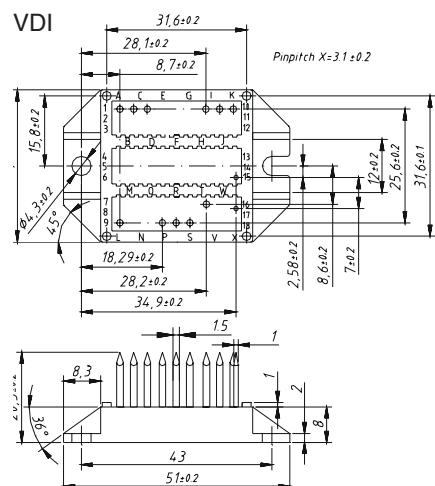
Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
V <sub>F</sub>	I <sub>F</sub> = 100 A; T <sub>VJ</sub> = 25°C T <sub>VJ</sub> = 125°C	2.3 1.7	2.7 V	V
I <sub>RM</sub> t <sub>rr</sub>	I <sub>F</sub> = 75 A; dI <sub>F</sub> /dt = 750 A/μs; T <sub>VJ</sub> = 125°C V <sub>R</sub> = 600 V; V <sub>GE</sub> = 0 V	79 220	A ns	
R <sub>thJC</sub> R <sub>thJH</sub>	with heatsink compound (0.42 K/m.K; 50 μm)	0.9	0.45 K/W K/W	



B3

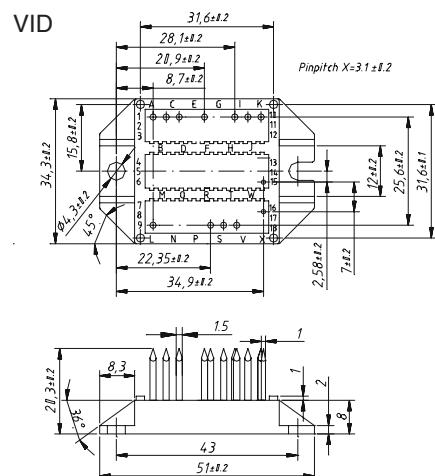
## Temperature Sensor NTC

Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
R <sub>25</sub>	T = 25°C	4.75	5.0	5.25 kΩ
B <sub>25/50</sub>		3375		K



## Module

Symbol	Conditions	Maximum Ratings		
T <sub>VJ</sub>		-40...+150		°C
T <sub>stg</sub>		-40...+150		°C
V <sub>ISOL</sub>	I <sub>ISOL</sub> ≤ 1 mA; 50/60 Hz	3000	V	~
M <sub>d</sub>	mounting torque (M4)	1.5 - 2.0 14 - 18	Nm lb.in.	
a	Max. allowable acceleration	50	m/s <sup>2</sup>	



Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
d <sub>s</sub>	Creepage distance on surface (Pin to heatsink)	11.2		mm
d <sub>A</sub>	Strike distance in air (Pin to heatsink)	11.2		mm
Weight		24		g

Data according to IEC 60747 and refer to a single transistor or diode unless otherwise stated.

IXYS reserves the right to change limits, test conditions and dimensions.

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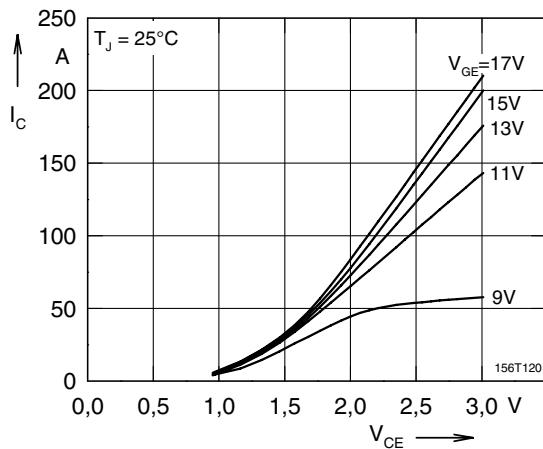


Fig. 1 Typ. output characteristics

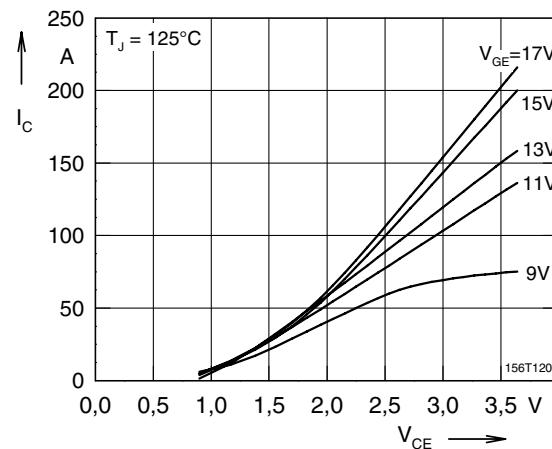


Fig. 2 Typ. output characteristics

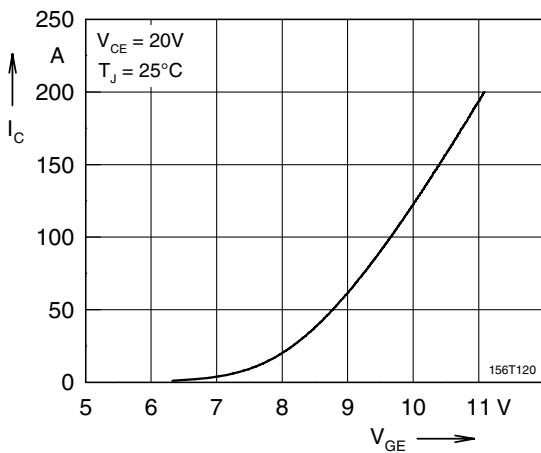


Fig. 3 Typ. transfer characteristics

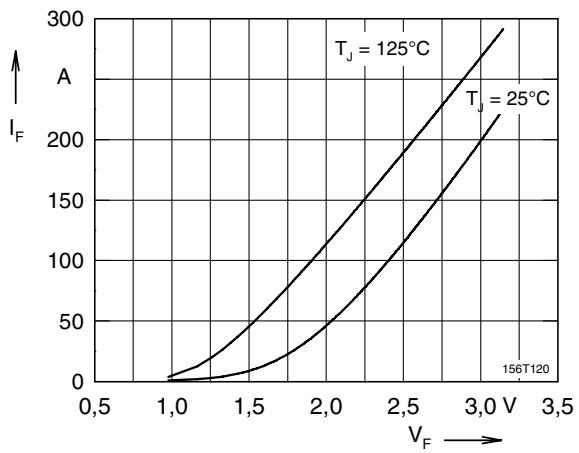


Fig. 4 Typ. forward characteristics of free wheeling diode

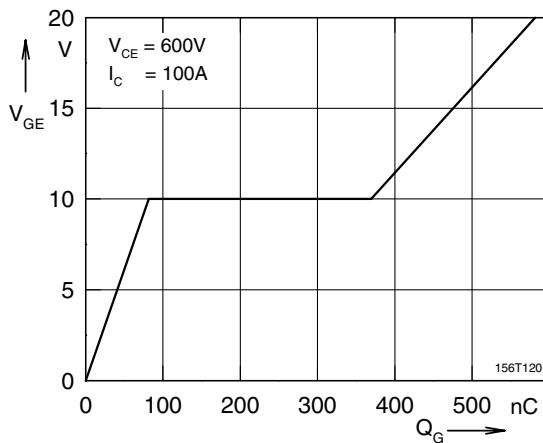


Fig. 5 Typ. turn on gate charge

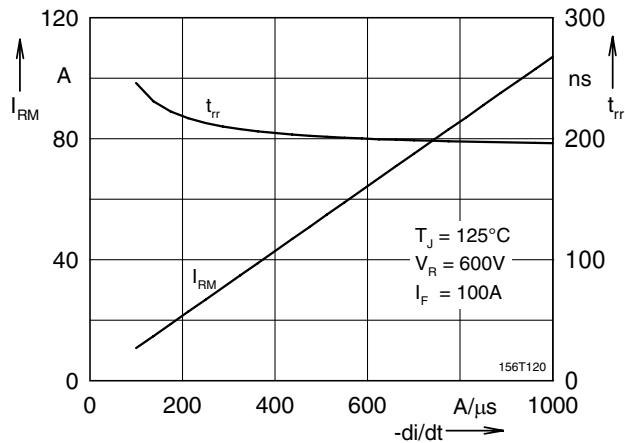


Fig. 6 Typ. turn off characteristics of free wheeling diode

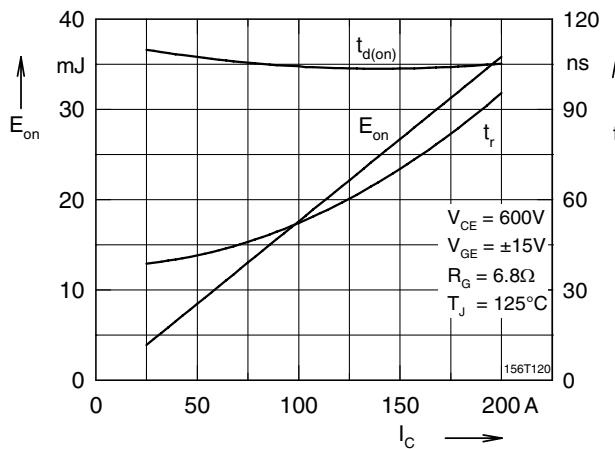


Fig. 7 Typ. turn on energy and switching times versus collector current

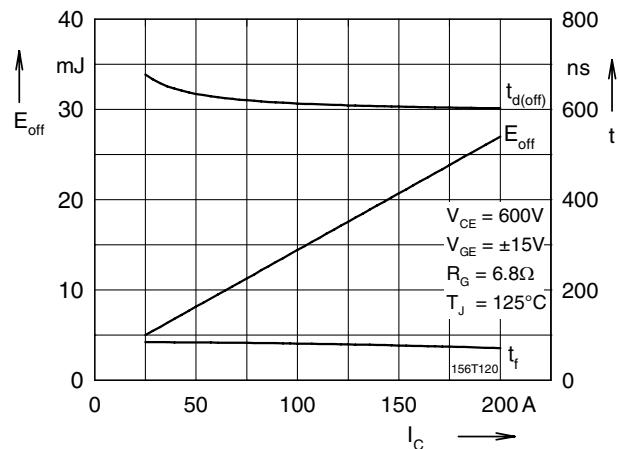


Fig. 8 Typ. turn off energy and switching times versus collector current

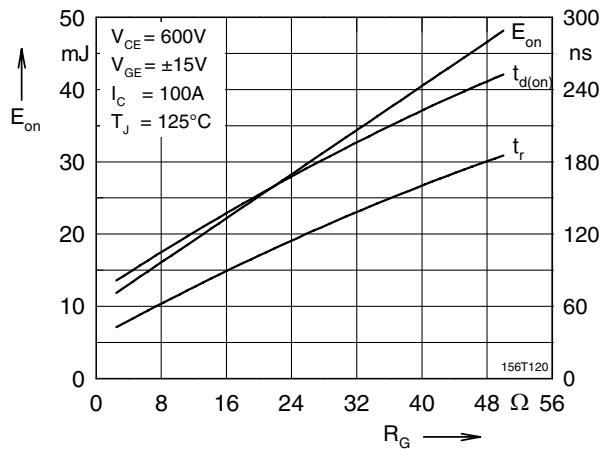


Fig. 9 Typ. turn on energy and switching times versus gate resistor

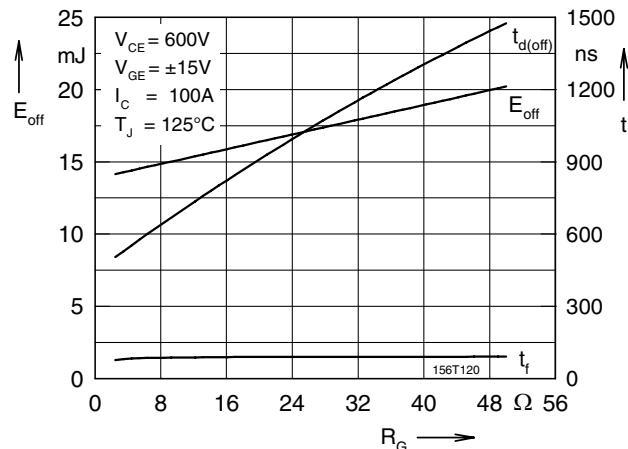


Fig.10 Typ. turn off energy and switching times versus gate resistor

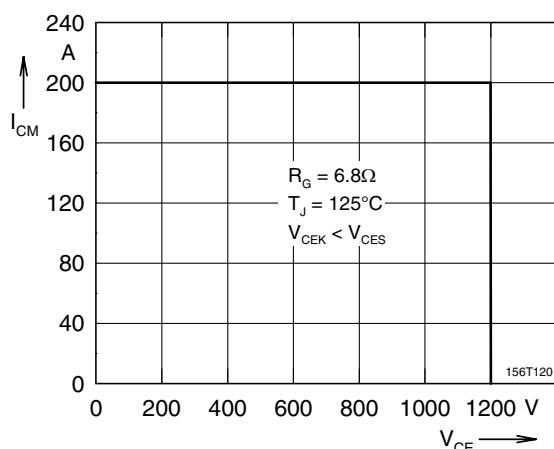


Fig. 11 Reverse biased safe operating area RBSOA

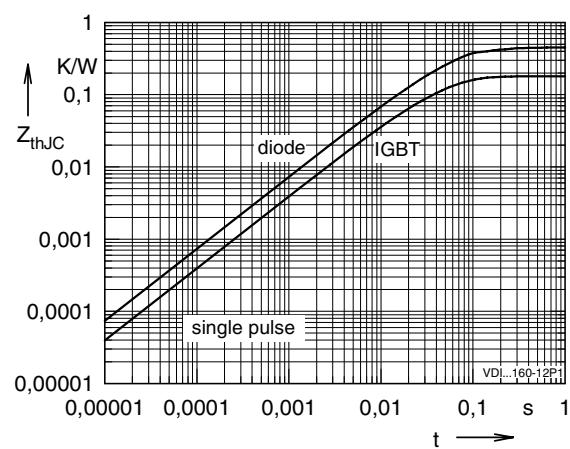


Fig. 12 Typ. transient thermal impedance